

**CLE SERIES**

**(0.80 mm) .0315"**

# COST-EFFECTIVE MICRO SOCKET

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?CLE](http://www.samtec.com?CLE)

**Insulator Material:** Black Liquid Crystal Polymer

**Contact Material:** BeCu

**Plating:** Au over 50 μ" (1.27 μm) Ni

**Current Rating (CLE/FTE):** 2.7 A per pin

(1 pin powered per row)

**Operating Temp Range:** -55 °C to +125 °C

**Contact Resistance:** 15 mΩ

**Insertion Depth:** Top Entry = (1.73 mm) .068"

to (3.18 mm) .125" with (0.38 mm) .015" wipe, or pass-through

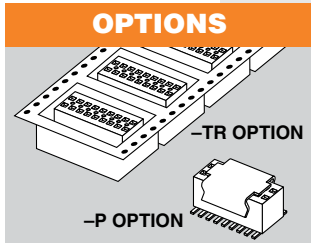
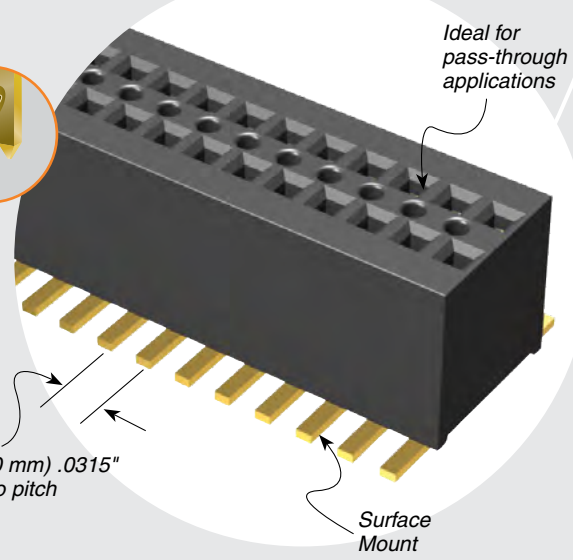
Bottom Entry = (3.23 mm) .127" minimum plus board thickness

**Normal Force:** 75 grams (0.73 N)

**Max Cycles:** 100 with 10 μ" (0.25 μm) Au

**RoHS Compliant:** Yes

Mates with: FTE, AW



**PROCESSING**

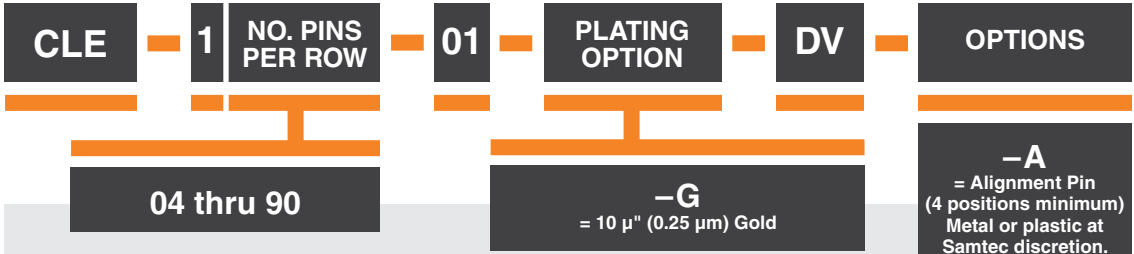
**Lead-Free Solderable:** Yes

**SMT Lead Coplanarity:** (0.10 mm) .004" max (04-65)

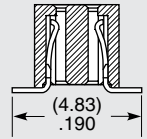
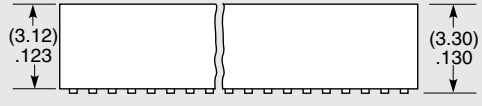
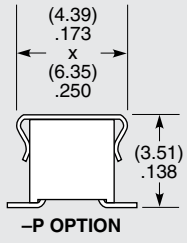
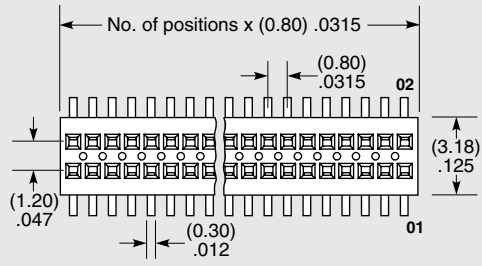
(0.15 mm) .006" max (66-90)

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



- A = Alignment Pin (4 positions minimum) Metal or plastic at Samtec discretion.
- K = (3.50 mm) .138" DIA Polyimide film Pick & Place Pad (8 positions minimum)
- P = Metal Pick & Place Pad (8 positions minimum)
- TR = Tape & Reel Packaging



**Note:** Some lengths, styles and options are non-standard, non-returnable.